

FOLEY & LARDNER

ATTORNEYS AT LAW

WASHINGTON HARBOUR
 SUITE 500
 3000 K STREET, N.W.
 WASHINGTON, D.C. 20007-5109
 TELEPHONE (202) 672-5300
 TELEX 904136

162/E
FAX COPY RECEIVED

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FOR: NAME Examiner J. Lee
 COMPANY Art Unit 2501
 FAX NUMBER 703 - 308 - 7724
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MESSAGE:

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Stephen B. Maebius
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No. 50169/105/ENPO

In re patent application of

Wallace T.Y. TANG

Group Art Unit: 2501

Serial No. 08/401,229

Examiner: J. Lee

Filed: March 9, 1995

For: IN-SITU REAL-TIME MONITORING TECHNIQUE AND APPARATUS
FOR ENDPOINT DETECTION OF THIN FILMS DURING
CHEMICAL/MECHANICAL POLISHING PLANARIZATIONSUPPLEMENTAL AMENDMENTAssistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Further to the Amendment filed on December 9, 1996, please amend the above-identified application as follows:

IN THE CLAIMS

Please add the following claims:

37-76. An apparatus for chemical mechanical polishing of a wafer, comprising

- (a) a rotatable polishing platen with an overlying polishing pad wetted with an abrasive slurry;
- (b) a rotatable chuck for holding the wafer against the polishing pad, the wafer comprising a semiconductor substrate underlying an oxide layer; and
- (c) and endpoint detector, comprising
 - (c1) a laser interferometer capable of generating a laser beam directed towards the wafer and detecting light reflected from the wafer, and
 - (c2) a hole formed through the platen and polishing pad allowing the laser beam to reflect off a section of the

JDL 10/21/98

35